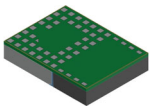
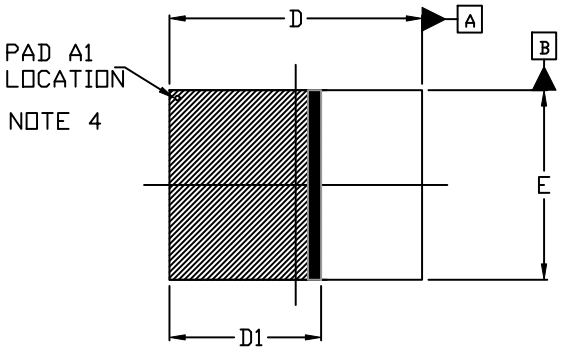
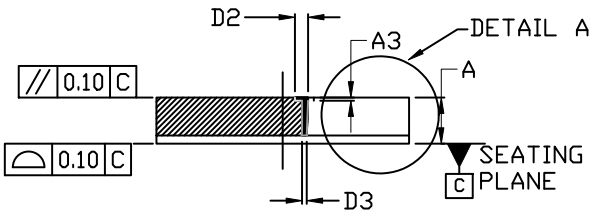


SIP51 8x6
CASE 127EY
ISSUE B

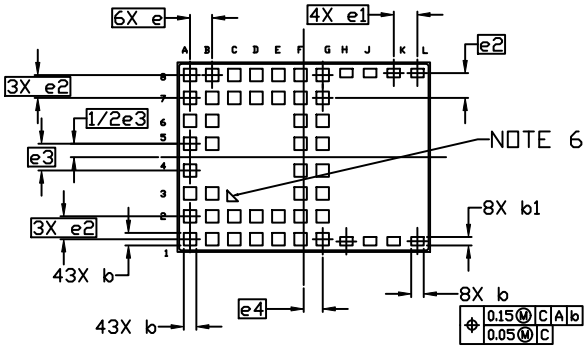
DATE 30 JUN 2020



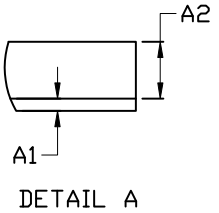
TOP VIEW



SIDE VIEW



BOTTOM VIEW

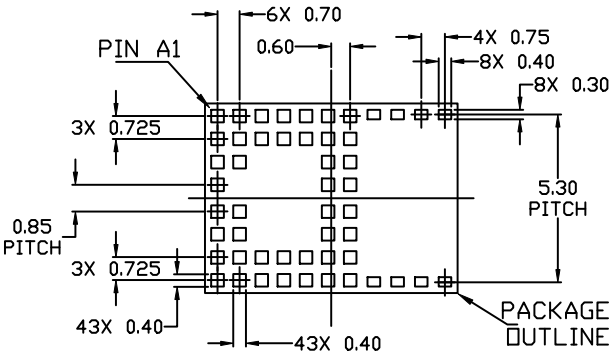


DETAIL A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. PIN 1 IDENTIFIER IS LOCATED HERE MAY APPEAR AS A CHAMFER, INK MARK, METALLIZED MARK, ETC.
5. REFER TO PRODUCT DATASHEET FOR SPECIFIC KEEP-OUT AREA AND GROUND PLANE REQUIREMENTS.
6. ORIENTATION MARKER ON BOTTOM SIDE USEABLE BY VISION RECOGNITION EQUIPMENT

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	1.36	1.46	1.56
A1	0.23	0.26	0.29
A2	1.13	1.20	1.27
A3		0.10 REF	
b	0.35	0.40	0.45
b1	0.225	0.275	0.325
D	7.90	8.00	8.10
D1		4.805 REF	
D2		0.42 REF	
D3		0.15 REF	
E	5.90	6.00	6.10
e		0.70 BSC	
e1		0.75 BSC	
e2		0.725 BSC	
e3		0.85 BSC	
e4		0.60 REF	



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*

A = Assembly Location
WL = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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